TOSHIBA Field Effect Transistor Silicon N Channel MOS Type

# SSM3K302T

Power Management Switch Applications High Speed Switching Applications

1.8 V drive

• Low ON-resistance:  $R_{on} = 131 \text{ m}\Omega \text{ (max) } (@V_{GS} = 1.8V)$ 

 $R_{OR} = 87m\Omega \text{ (max) (@V_{GS} = 2.5V)}$  $R_{OR} = 71 \text{ m}\Omega \text{ (max) (@V_{GS} = 4.0V)}$ 

# Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DS</sub>	30	V	
Gate-source voltage		$V_{GSS}$	± 12	٧	
Drain current	DC	I <sub>D</sub>	3.0	А	
	Pulse	I <sub>DP</sub>	6.0		
Drain power dissipation		P <sub>D (Note 1)</sub>	700	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the

Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

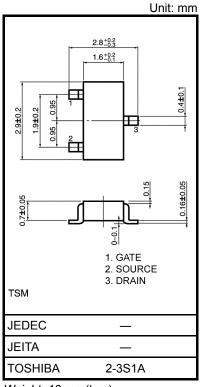
Note 1: Mounted on an FR4 board.

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ t}, \text{ Cu Pad: } 645 \text{ mm}^2)$ 

# **Electrical Characteristics (Ta = 25°C)**

Charact	eristic	Symbol	Test Condition		Min	Тур.	Max	Unit
Drain–source breakdown voltage	V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0$		30	_	_	V	
Drain-source breakdown voltage		V (BR) DSX	$I_D = 1 \text{ mA}, V_{GS} = -12 \text{ V}$		18	_	_	٧
Drain cutoff current	t	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0		_	_	1	μА
Gate leakage curre	nt	I <sub>GSS</sub>	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$		_	_	±1	μА
Gate threshold volt	age	V <sub>th</sub>	$V_{DS} = 3 \text{ V}, I_D = 1 \text{ mA}$		0.4	_	1.0	V
Forward transfer ad	dmittance	Y <sub>fs</sub>	$V_{DS} = 3 \text{ V}, I_{D} = 2 \text{ A}$	(Note2)	3.8	7.7		S
Drain-source ON-resistance		R <sub>DS (ON)</sub>	I <sub>D</sub> = 2.0 A, V <sub>GS</sub> = 4.0 V	(Note2)	_	52	71	mΩ
			I <sub>D</sub> = 1.0 A, V <sub>GS</sub> = 2.5 V	(Note2)		64	87	
			I <sub>D</sub> = 0.5 A, V <sub>GS</sub> = 1.8 V	(Note2)		81	131	
Input capacitance		C <sub>iss</sub>				270		
Output capacitance		Coss	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		_	56	_	pF
Reverse transfer capacitance		C <sub>rss</sub>				47	_	
		$Q_g$	V <sub>DS</sub> = 15 V, I <sub>DS</sub> = 3.0 A			4.3	_	nC
		$Q_{gs}$				2.8	_	
Gate-Drain Charge		$Q_{gd}$	V <sub>GS</sub> = 4 V		_	1.5	_	
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = 10 \text{ V}, I_D = 2 \text{ A},$ $V_{GS} = 0 \text{ to } 2.5 \text{ V}, R_G = 4.7 \Omega$		_	20	_	
	Turn-off time	t <sub>off</sub>				31	_	ns
Drain-source forward voltage		V <sub>DSF</sub>	$I_D = -3.0 \text{ A}, V_{GS} = 0 \text{ V}$	(Note2)		- 0.85	- 1.2	V

Note2: Pulse test

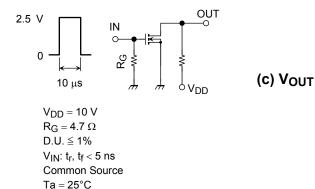


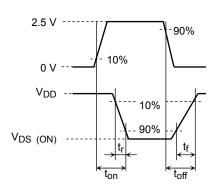
Weight: 10 mg (typ.)

# **Switching Time Test Circuit**

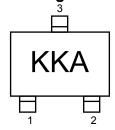
## (a) Test Circuit

## (b) V<sub>IN</sub>

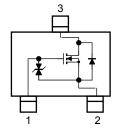




#### Marking



## **Equivalent Circuit (top view)**



# **Notice on Usage**

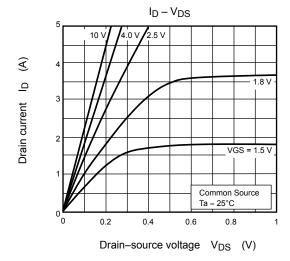
 $V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D$  = 1 mA for this product. For normal switching operation,  $V_{GS\ (on)}$  requires a higher voltage than  $V_{th}$  and  $V_{GS\ (off)}$  requires a lower voltage than  $V_{th}$ .

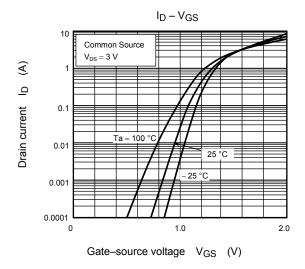
(The relationship can be established as follows:  $V_{GS (off)} < V_{th} < V_{GS (on)}$ .)

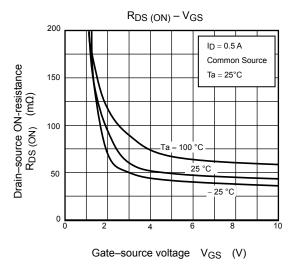
Take this into consideration when using the device.

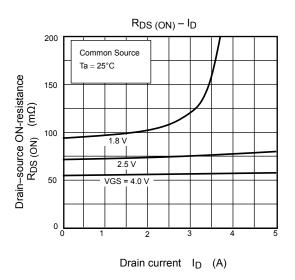
## **Handling Precaution**

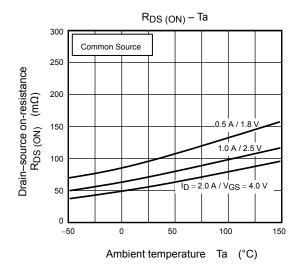
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

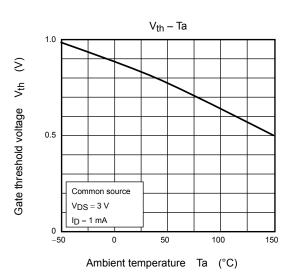




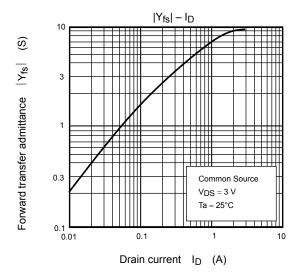


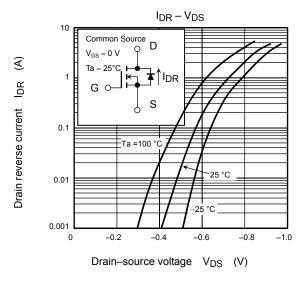


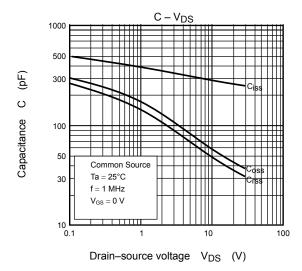


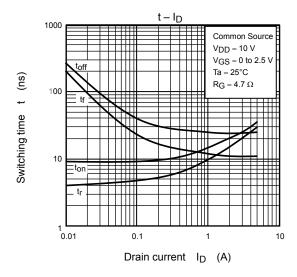


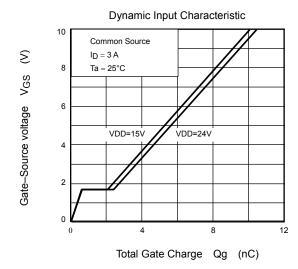
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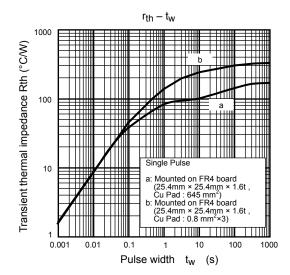


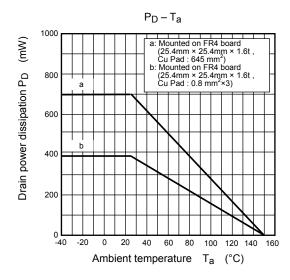






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20070701-EN GENERAL

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